EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	98777	(die or wafwer) same order$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/07 18:42
S2	25	(die or wafer) with order$3 and ic and "705"/$$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 12:53
S3	33	(die or wafer) with order$3 and ic and pricing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 12:50
S4	2	"20020046147"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 15:30
S5	171	(die or wafer or chip$1 or ic) and customer with order$3 and ic and pricing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 12:51
S6	69	(die or wafer or chip$1 or ic) and customer with order$3 and ic and pricing and "705"/$$	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 12:55
S7	59	"705"/$$ and (@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (die or wafer$1 or chip$1 or ic) and customer with order$3 and ic and pricing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 12:56

EAST Search History

S8	59	"705"/$$ and (@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (reticle or die or wafer$1 or chip$1 or ic) and customer with order$3 and ic and pricing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:00
S9	0	"705"/$$ and (@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (reticle or die or wafer$1 or chip$1 or ic) and customer with order$3 and ic and pricing and schinella	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:00
S10	0	("20040006485" and "5663017")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:01
S11	50	("20040006485" or "5663017")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:02
S12	8	("20040006485" or "5663017") and order$3 with form$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:03
S13	6	("20040006485" or "5663017") and (form41 or document$1 or bill or bom or order near2 form$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:04
S14	50	("20040006485" or "5663017") and (form$1 or document$1 or bill or bom or order near2 form$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:06

S15	50	("20040006485" or "5663017")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:08
S16	52	("20040006485" or "5663017" or "20020143424")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 13:08
S17	2	"20030149953"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 15:31
S18	2	"20030144953"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/09 15:31
S19	2875	(die or wafer) and order$3 near3 (form$1 or sheet$1) and extract$3 and semiconductor$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:38
S20	1157	(die or wafer) and order$3 near3 (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:39
S21	60	(die or wafer) and customer near4 order$3 and (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:39

S22	32	(die or wafer) and customer near4 order$3 and (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:40
S23	23	"705"/$$ and (@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (die or wafer) and customer near4 order$3 and (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:40
S24	130	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (chip$1 or die or wafer) and customer with order$3 and (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:42
S25	25	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and (chip$1 or die or wafer) with (pric$3 or cost$3 or quote$1 or rfq) and customer with order$3 and (form$1 or sheet$1) and extract$3 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:44
S26	2	weed and (chip$1 or die or wafer) with (pric$3 or cost$3 or quote$1 or rfq) and customer with order$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:46
S27	19	weed and (chip$1 or die or wafer) with (pric$3 or cost$3 or quote$1 or rfq) and customer and order$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:46

S28	104	weed and (chip$1 or die or wafer$1) with (pric$3 or cost$3 or quote$1 or rfq)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:47
S29	0	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global near3 pricing and (chip$1 or die or wafer) and customer$1 and order$3 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:50
S30	0	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global near3 pricing and (chip$1 or die or wafer) and customer$1 and semiconductor$1 and analysis and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:50
S31	0	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global near3 pricing and (chip$1 or die or wafer) and customer$1 and semiconductor$1 and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:50
S32	11	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global with pricing and (chip$1 or die or wafer) and customer$1 and semiconductor$1 and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:50
S33	17	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global with pricing and (chip$1 or die or wafer) and customer$1 and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:51

S34	10	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global with pricing and (chip$1 or die or wafer$1) same (pric$3 or cost$3 or fee or fees or charg$3) and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:52
S35	21	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and global same pricing and (chip$1 or die or wafer$1) same (pric$3 or cost$3 or fee or fees or charg$3) and (report$3 or summar$3) and sales	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:53
S36	4	(@ad<"20040209" or @pd<"20040209" or @rlad<"20040209" or @prad<"20040209") and negotiat$4 same pric$3 with (chip$1 or die or wafer$1 or ic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/22 00:55